

DECLARATION

As the below-named inventor, I declare that:

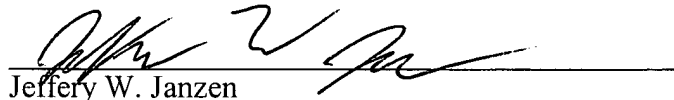
My residence, post office address, and citizenship are as stated below under my name.

I believe I am the original, first, and sole inventor of the invention entitled "SYSTEM AND METHOD FOR OPTIMIZING INTERCONNECTIONS OF COMPONENTS IN A MULTICHIP MEMORY MODULE," which is described and claimed in the foregoing application and for which a patent is sought.

I have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment specifically referred to herein (if any).

I acknowledge my duty to disclose information of which I am aware which is material to patentability and examination of this application in accordance with 37 C.F.R. § 1.56(a).

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.

  
Jeffery W. Janzen

Date 3-12-04

Residence : City of Meridian, County of Ada  
State of Idaho  
Citizenship : United States of America  
P.O. Address : 2727 North Silverleaf Way  
Meridian, Idaho 83642

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Jeffery W. Janzen Attorney Docket No.: 501286.01  
Filed : Concurrently herewith  
Title : SYSTEM AND METHOD FOR OPTIMIZING INTERCONNECTIONS OF COMPONENTS  
IN A MULTICHIP MEMORY MODULE

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Mail Stop Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73(b) AND POWER OF ATTORNEY**

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventor.

Assignee hereby appoints EDWARD W. BULCHIS, Reg. No. 26,847; PAUL T. MEIKLEJOHN, Reg. No. 26,569; KIMTON N. ENG, Reg. No. 43,605; BRIAN C. PARK, Reg. No. 45,519; MARK W. ROBERTS, Reg. No. 46,160; STEVEN H. ARTERBERRY, Reg. No. 46,314; PAUL F. RUSYN, Reg. No. 42,118; JAMES ACKLEY, Reg. No. 45,695; RONALD BROWN, Reg. No. 29,016; DAVID BRUHN, Reg. No. 36,762; KEVIN CHAPPLE, Reg. No. 44,072; W. ROBINSON CLARK, Reg. No. 41,530; SHANE COLEMAN, Reg. No. 44,623; GREGORY DURBIN, Reg. No. 42,503; DANIEL FISHER, Reg. No. 34,162; DAVID FRONEK, Reg. No. 25,678; ANTHONY GANGEMI, Reg. No. 42,565; MICHAEL GILCHRIST, Reg. No. 40,619; THERESA HANKES, Reg. No. 45,501; JOHN HARROP, Reg. No. 41,817;

BRAD HATTENBACH, Reg. No. 42,642; REED HEIMBECHER, Reg. No. 36,353; CRAIG HEMENWAY, Reg. No. 44,759; STUART HEMPHILL, Reg. No. 28,084; MARK HOGGE, Reg. No. 31,622; JOHN KENNEDY, Reg. No. 42,717; JASON KRAUS, Reg. No. 42,765; BRIAN LAURENZO, Reg. No. 34,207; KENNETH LEVITT, Reg. No. 39,747; KURT LEYENDECKER, Reg. No. 42,799; SCOTT MARKS, Reg. No. 44,902; KEITH MONTGOMERY, Reg. No. 45,245; ALDO NOTO, Reg. No. 35,628; LEE OSMAN, Reg. No. 38,260; DEVAN PADMANABHAN, Reg. No. 38,262; JAMES PINTO, Reg. No. 40,774; GARY POLUMBUS, Reg. No. 25,364; SCOTT ROTHENBERGER, Reg. No. 41,277; LEONARD SANTISI, Reg. No. 24,135; ROBERT SCHEFFEL, Reg. No. 43,090; AMI SHAH, Reg. No. 41,143; MIRIAM SOHN, Reg. No. 35,368; HERMES SOYEZ, Reg. No. 45,852; GERALD SULLIVAN, Reg. No. 37,243; MARK THOMAS, Reg. No. 37,953; JON TUTTLE, Reg. No. 25,713; MEGAN VALENTINE, Reg. No. 47,149; LANCE VIETZKE, Reg. No. 36,708; SEAN WOODEN, Reg. No. 43,997; and the attorneys and agents associated with the firm of **DORSEY & WHITNEY LLP**, **Customer Number 27,076**, along with MICHAEL L. LYNCH, Reg. No. 30,871; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of MICRON TECHNOLOGY, INC., 8000 South Federal Way, Boise, Idaho 83716-9632, as its attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. Please direct all telephone calls to **Edward W. Bulchis** at (206) 903-8800 and telecopies to (206) 903-8820.

Please direct all communications to:

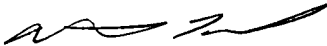
Edward W. Bulchis, Esq.  
**Customer No. 27,076**  
 Dorsey & Whitney LLP  
 1420 Fifth Avenue, Suite 3400  
 Seattle, Washington 98101  
 (206) 903-8800

Pursuant to 37 C.F.R. § 3.73(b), the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., filed concurrently herewith for recording, a copy of which is

attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC.  
ASSIGNEE

March 29, 2008  
DATE

  
Michael L. Lynch  
Chief Patent Counsel

Enclosure:  
Copy of Assignment

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Jeffery W. Janzen

Filed : Concurrently herewith

For : SYSTEM AND METHOD FOR  
OPTIMIZING INTERCONNECTIONS  
OF COMPONENTS IN A MULTICHIP  
MEMORY MODULE

Docket No. 501286.01

Disclosure No. 02-1152

A S S I G N M E N T :

  X   Enclosed for recording

       Previously recorded

Date: \_\_\_\_\_

Reel: \_\_\_\_\_

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "**SYSTEM AND METHOD FOR OPTIMIZING INTERCONNECTIONS OF COMPONENTS IN A MULTICHIP MEMORY MODULE**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

